

MULTILAYER CERAMIC SUBSTRATE WITH ANCHORED PAD

ABSTRACT

Disclosed is a multilayer ceramic substrate (340) having an outer pad (316), for example an I/O pad, which is anchored to an inner pad (324) of the multilayer ceramic substrate (340) by either a plurality of vias or one large via (314). The outer pad (316) and vias are made of high metal material, preferably 100% metal, so they won't adhere very well to the ceramic substrate (340). The inner pad (324) is a composite metal/ceramic material which will bond very well to the ceramic substrate (340).

FIG 7



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